Fast Current Mirror

ABSOLUTE MAXIMUM RATINGS

Voltage Range on MIRIN, MIROUT,
and DIODE Relative to GND0.3V to +80V
Voltage Range on MIR
Relative to GND0.3V to (V _{DIODE} + 0.6V)
Continuous Power Dissipation ($T_A = +70^{\circ}C$)
SOT23 (derate 13.4mW/°C above +70°C) 1072.4mW

Operating Junction Temperature Range40°C to +150°C	;
Storage Temperature Range55°C to +135°C	;
Lead Temperature (soldering, 10s)+300°C	;
Soldering Temperature (reflow)+260°C	;

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{MIRIN} = 2.97V to 76V, T_A = -40°C to +85°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
MIRIN Voltage	V _{MIRIN}		2.97		76	V	
MIRIN Current	I _{MIRIN}	I _{MIROUT} = 2.5mA			4.4	mA	
Diode Forward Current	I _{DF}				5	mA	
Diode Forward Voltage	V _{DF}	$I_{DF} = 100\mu A, T_A = +25^{\circ}C$		0.6		V	
		$I_{DF} = 5mA, T_A = +25^{\circ}C$			1.25		
MIROUT Current Limit	IMIROUT	DS3920T-001 version, $T_A = +25^{\circ}C$	10	20	40	mA	
		DS3920T-002 version, $T_A = +25^{\circ}C$	2.8	4.4	8		
MIROUT Series Resistance	R _{AGC}	(Note 1)	100			Ω	
MIR to MIROUT Ratio	K _{MIR}	1µA to 2.5mA	0.190	0.200	0.210	A/A	
		I _{MIROUT} > 2.5mA	0.180	0.200	0.220		
Power-Supply Rejection Ratio	$(\Delta I_{MIR}/I_{MIR})$ $/\Delta V_{MIRIN}$	V _{MIRIN} = 3V (Note 2)		4800	15,000	ppm/V	
		V _{MIRIN} = 30V or 60V (Notes 2, 3)		100	500		
MIR Current Rise Time (20%/80%)	t _{RC}	(Note 4)		30		ns	
Thermal Shutdown Temperature	T _{SHDN}	(Note 3)		+150		°C	
Thermal Shutdown Hysteresis	T _{HYST}	(Note 3)		20		°C	

Note 1: See the *Typical Application Circuit*.

Note 2: 1V DC change applied to MIRIN; 100 μ A at MIROUT; 4.99k Ω load to ground on MIR.

Note 3: Guaranteed by design; not production tested.

Note 4: Rising MIROUT transition from 10 μ A to 1mA; 15V < V_{OUT} < 76V.

Fast Current Mirror

Typical Operating Characteristics

MIRIN CURRENT vs. MIROUT CURRENT

100

10

1

0.1

0.01

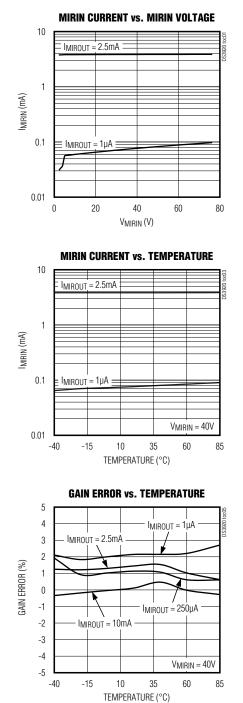
0.001

IMIRIN (mA)

 $V_{MIRIN} = 40V$

₩

0.01



 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

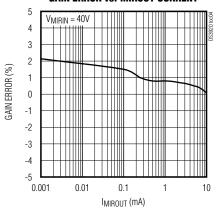
GAIN ERROR vs. MIROUT CURRENT

0.1

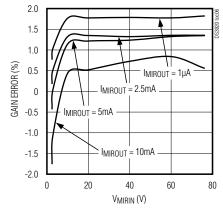
I_{MIROUT} (mA)

1

10



GAIN ERROR vs. MIRIN VOLTAGE

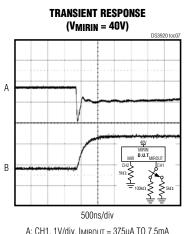


Maxim Integrated

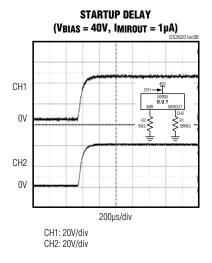
Fast Current Mirror

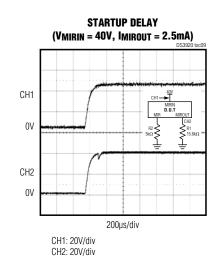
Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

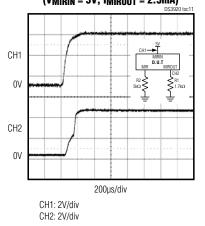


A: CH1, 1V/div, I_{MIROUT} = 375µA TO 7.5mA A: CH2; 5V/div, I_{MIR} = 75µA TO 1.5mA





STARTUP DELAY (VMIRIN = 5V, IMIROUT = 1µA) DS32010c10 CH1 OV CH2 OV DU CH2 OV CH1: 2V/div CH1: 2V/div CH2: 2V/div STARTUP DELAY (V_{MIRIN} = 5V, I_{MIROUT} = 2.5mA)

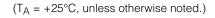


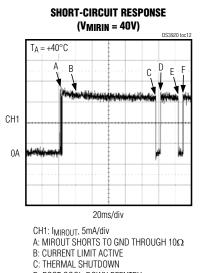
Maxim Integrated

5

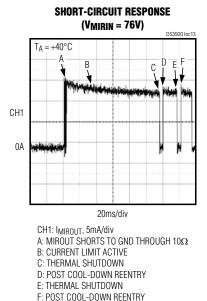
DS3920

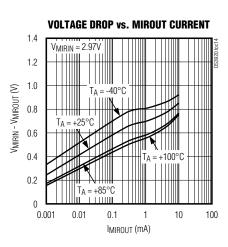
Fast Current Mirror





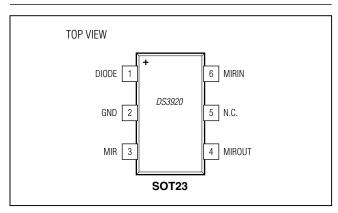






Pin Description

Pin Configuration



PIN	NAME	FUNCTION
1	DIODE	Protection Diode. External potential used for voltage clamping of V _{MIR} . If unused, this pin can be left unconnected.
2	GND	Ground
3	MIR	Mirror Current Monitor Output, 5:1 Ratio
4	MIROUT	Current Mirror Voltage Output. Connect to photodiode bias pin. Photodiode provides reference current for the mirror.
5	N.C.	No Connection. Not internally connected.
6	MIRIN	Current Voltage Bias

Typical Operating Characteristics (continued)

Maxim Integrated

Fast Current Mirror

Detailed Description

The DS3920 provides a fast, precision current mirror for photodiode-monitoring applications. The current mirror is accurate across a large dynamic range. The mirror response time is fast enough to comply with GPON Rx burst-mode monitoring requirements. The device has a built-in current limiting feature to protect photodiodes from large signal inputs, and an included thermal shutdown. A diode is provided to limit the voltage at the MIR output.

Current Mirror

The mirror output is typically connected to an analogto-digital converter (ADC) using a resistor to convert the mirrored current into a voltage. The resistor to ground should be selected so that the ADC's full-scale voltage is reached when the maximum mirrored current is reached. For example, given that the maximum monitored current through the APD is 2mA, 1.25V ADC full scale, and a 5:1 mirror ratio, the correct resistor is approximately $3.2k\Omega$.

The mirror response time is dominated by the amount of capacitance placed on the output.

Current Clamp

The device features a current clamping circuit to protect the photodiode by limiting the amount of current from MIROUT to no more than I_{MIROUT} . See the <u>Ordering</u> Information for available current clamp options.

Diode Protection

A diode is internally connected from the MIR to DIODE pins. This enables an external voltage applied to DIODE to limit the voltage on MIR. The voltage applied to DIODE should be equal to the desired V_{MIR} limit minus the diode forward voltage drop, or $V_{MIR} - V_{DF}$.

Thermal Shutdown

As a safety feature, the device has a thermal shutdown circuit that turns off the MIROUT and MIR currents when the internal die temperature exceeds T_{SHDN} . The thermal shutdown mechanism has a built-in hysteresis of T_{HYST} . Thus, the MIROUT and MIR currents resume once the device has cooled to T_{SHDN} - T_{HYST} .

Ordering Information

PART	TEMP RANGE	TYP CURRENT LIMIT (mA)	PIN-PACKAGE
DS3920T-001+	-40°C to +85°C	20	6 SOT23
DS3920T-001+T	-40°C to +85°C	20	6 SOT23
DS3920T-002+	-40°C to +85°C	4.4	6 SOT23
DS3920T-002+T	-40°C to +85°C	4.4	6 SOT23

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

Package Information

For the latest package outline information and land patterns (footprints), go to <u>www.maximintegrated.com/packages</u>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
6 SOT23	U6SN+1	<u>21-0058</u>	<u>90-0175</u>

7

Fast Current Mirror

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	3/11	Initial release	—
1	8/11	Changed the MIROUT -002 version current limit value from 2.9mA (typ) to 4.4mA (typ); updated the <i>Electrical Characteristics</i> I _{MIROUT} values for -002 version from 2mA (min), 2.9mA (typ), 4.4mA (max) to 2.8mA (min), 4.4mA (typ), 8mA (max) and added $T_A = +25^{\circ}C$ test conditions	1, 2, 6
2	12/11	Added RFILTER and ROUT resistor values to the Typical Application Circuit	1



Maxim Integrated cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim Integrated product. No circuit patent licenses are implied. Maxim Integrated reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.

Maxim Integrated 160 Rio Robles, San Jose, CA 95134 USA 1-408-601-1000

© 2011 Maxim Integrated Products, Inc.

Maxim Integrated and the Maxim Integrated logo are trademarks of Maxim Integrated Products, Inc.